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(75) Inventors/Applicants (for US only): **NISHIMOTO, Keiji. NAGAI, Hideo.**

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(74) Agents: **NAKAJIMA, Shiro** et al.; 6F, Yodogawa 5-Bankan, 2-1, Toyosaki 3-chome, Kita-ku, Osaka-shi, Osaka 5310072 (JP).

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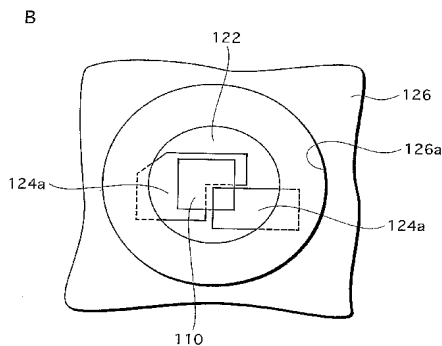
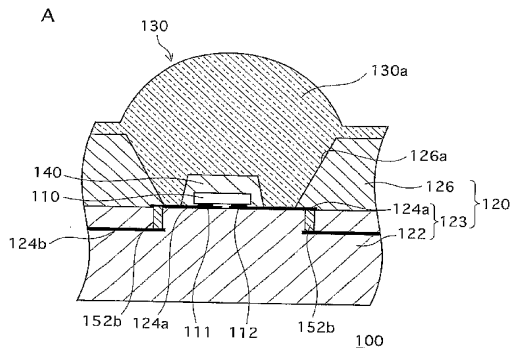
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(71) Applicant (for all designated States except US): **MAT-SUSHITA ELECTRIC INDUSTRIAL CO., LTD.** [JP/JP]; 1006, Oaza Kadoma, Kadoma-shi, Osaka, 5718501 (JP).

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(54) Title: LED MOUNTING MODULE, LED MODULE, MANUFACTURING METHOD OF LED MOUNTING MODULE, AND MANUFACTURING METHOD OF LED MODULE



(57) Abstract: The following explains an LED module that can achieve favorable light extraction efficiency without increasing a cost. An LED module (100) includes LED devices (110), an LED mounting module (120) on which the LED devices (110) are mounted, and a lens board (130) attached to a front surface of the LED mounting module (120). The LED mounting module (120) includes a printed wiring board (123) and a reflecting board (126). The printed wiring board (123) is an insulation board (122) on which a wiring pattern (124), used to mount the LED devices (110), is formed. The reflecting board (126) is made of a resin material, and has therein reflecting holes (126a) provided in correspondence with locations, on the printed wiring board (123), where the LED devices (110) are mounted. The reflecting board (126) and the printed wiring board (123) are directly adhered to each other at their surfaces that face each other.



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